Features

- Compatible with MCS-51[®] Products
- 4K Bytes of In-System Programmable (ISP) Flash Memory – Endurance: 1000 Write/Erase Cycles
- 4.0V to 5.5V Operating Range
- Fully Static Operation: 0 Hz to 33 MHz
- Three-level Program Memory Lock
- 128 x 8-bit Internal RAM
- 32 Programmable I/O Lines
- Two 16-bit Timer/Counters
- Six Interrupt Sources
- Full Duplex UART Serial Channel
- Low-power Idle and Power-down Modes
- Interrupt Recovery from Power-down Mode
- Watchdog Timer
- Dual Data Pointer
- Power-off Flag
- Fast Programming Time
- Flexible ISP Programming (Byte and Page Mode)

Description

The AT89S51 is a low-power, high-performance CMOS 8-bit microcontroller with 4K bytes of in-system programmable Flash memory. The device is manufactured using Atmel's high-density nonvolatile memory technology and is compatible with the industry-standard 80C51 instruction set and pinout. The on-chip Flash allows the program memory to be reprogrammed in-system or by a conventional nonvolatile memory programmer. By combining a versatile 8-bit CPU with in-system programmable Flash on a monolithic chip, the Atmel AT89S51 is a powerful microcontroller which provides a highly-flexible and cost-effective solution to many embedded control applications.

The AT89S51 provides the following standard features: 4K bytes of Flash, 128 bytes of RAM, 32 I/O lines, Watchdog timer, two data pointers, two 16-bit timer/counters, a five-vector two-level interrupt architecture, a full duplex serial port, on-chip oscillator, and clock circuitry. In addition, the AT89S51 is designed with static logic for operation down to zero frequency and supports two software selectable power saving modes. The Idle Mode stops the CPU while allowing the RAM, timer/counters, serial port, and interrupt system to continue functioning. The Power-down mode saves the RAM contents but freezes the oscillator, disabling all other chip functions until the next external interrupt or hardware reset.



8-bit Microcontroller with 4K Bytes In-System Programmable Flash

AT89S51



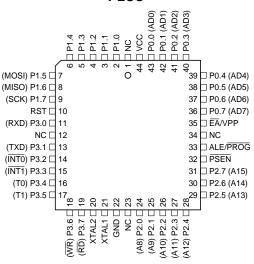


Pin Configurations

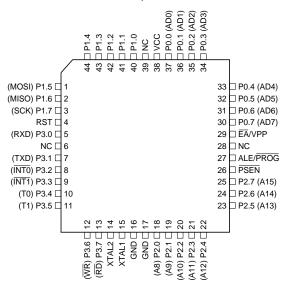
PDIP

1			1
P1.0 🗆	1	40	□vcc
P1.1 🗆	2	39	D P0.0 (AD0)
P1.2 🗆	3	38	D P0.1 (AD1)
P1.3 🗆	4	37	DP0.2 (AD2)
P1.4 🗆	5	36	DP0.3 (AD3)
(MOSI) P1.5 [6	35	D P0.4 (AD4)
(MISO) P1.6 [7	34	D P0.5 (AD5)
(SCK) P1.7 🗆	8	33	DP0.6 (AD6)
RST 🗆	9	32	DP0.7 (AD7)
(RXD) P3.0 🗆	10	31	□ EA/VPP
(TXD) P3.1 🗆	11	30	ALE/PROG
(INT0) P3.2 🗆	12	29	D PSEN
(INT1) P3.3 🗆	13	28	🗆 P2.7 (A15)
(T0) P3.4 🗆	14	27	🗆 P2.6 (A14)
(T1) P3.5 🗆	15	26	🗆 P2.5 (A13)
(WR) P3.6 🗆	16	25	🗆 P2.4 (A12)
(RD) P3.7 🗆	17	24	🗆 P2.3 (A11)
XTAL2 🗆	18	23	🗆 P2.2 (A10)
XTAL1 🗆	19	22	🗆 P2.1 (A9)
GND 🗆	20	21	🗆 P2.0 (A8)

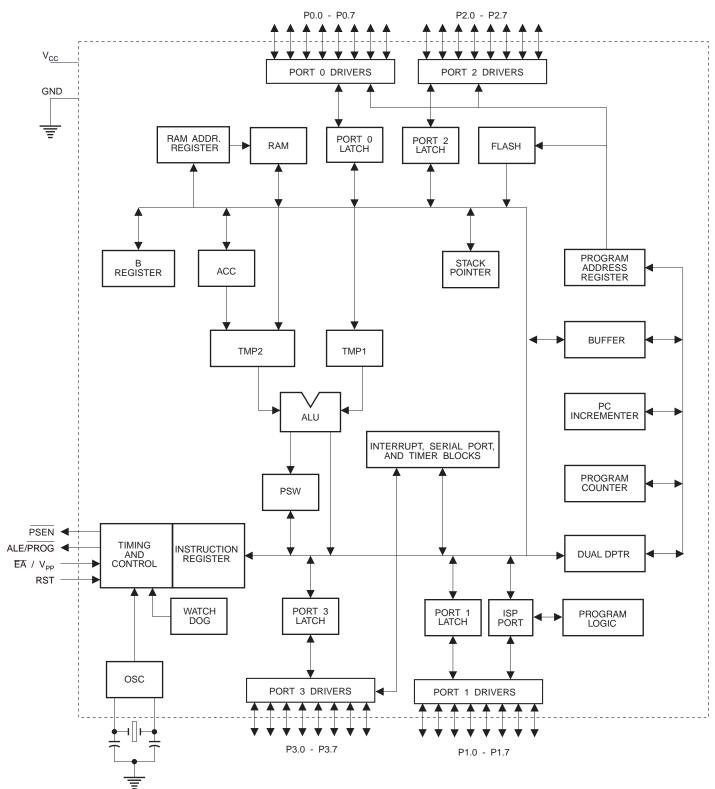
PLCC







Block Diagram







Pin Description

- VCC Supply voltage.
- GND Ground.
- Port 0 Port 0 is an 8-bit open drain bidirectional I/O port. As an output port, each pin can sink eight TTL inputs. When 1s are written to port 0 pins, the pins can be used as high-impedance inputs.

Port 0 can also be configured to be the multiplexed low-order address/data bus during accesses to external program and data memory. In this mode, P0 has internal pull-ups.

Port 0 also receives the code bytes during Flash programming and outputs the code bytes during program verification. **External pull-ups are required during program verification**.

Port 1 Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. The Port 1 output buffers can sink/source four TTL inputs. When 1s are written to Port 1 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current (I_{IL}) because of the internal pull-ups.

Port 1 also receives the low-order address bytes during Flash programming and verification.

Port Pin	Alternate Functions			
P1.5	MOSI (used for In-System Programming)			
P1.6	MISO (used for In-System Programming)			
P1.7	SCK (used for In-System Programming)			

Port 2 Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. The Port 2 output buffers can sink/source four TTL inputs. When 1s are written to Port 2 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally being pulled low will source current (I_{IL}) because of the internal pull-ups.

Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @ DPTR). In this application, Port 2 uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ RI), Port 2 emits the contents of the P2 Special Function Register.

Port 2 also receives the high-order address bits and some control signals during Flash programming and verification.

Port 3 Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}) because of the pull-ups.

Port 3 receives some control signals for Flash programming and verification.

Port 3 also serves the functions of various special features of the AT89S51, as shown in the following table.

AT89S51

Port Pin	Alternate Functions			
P3.0	RXD (serial input port)			
P3.1	TXD (serial output port)			
P3.2	INTO (external interrupt 0)			
P3.3	INT1 (external interrupt 1)			
P3.4	T0 (timer 0 external input)			
P3.5	T1 (timer 1 external input)			
P3.6	WR (external data memory write strobe)			
P3.7	RD (external data memory read strobe)			

RST Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device. This pin drives High for 98 oscillator periods after the Watchdog times out. The DIS-RTO bit in SFR AUXR (address 8EH) can be used to disable this feature. In the default state of bit DISRTO, the RESET HIGH out feature is enabled.

ALE/PROG Address Latch Enable (ALE) is an output pulse for latching the low byte of the address during accesses to external memory. This pin is also the program pulse input (PROG) during Flash programming.

In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external data memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX or MOVC instruction. Otherwise, the pin is weakly pulled high. Setting the ALE-disable bit has no effect if the microcontroller is in external execution mode.

PSEN Program Store Enable (PSEN) is the read strobe to external program memory.

When the AT89S51 is executing code from external program memory, PSEN is activated twice each machine cycle, except that two PSEN activations are skipped during each access to external data memory.

EA/VPP External Access Enable. EA must be strapped to GND in order to enable the device to fetch code from external program memory locations starting at 0000H up to FFFFH. Note, however, that if lock bit 1 is programmed, EA will be internally latched on reset.

 \overline{EA} should be strapped to V_{CC} for internal program executions.

This pin also receives the 12-volt programming enable voltage (V_{PP}) during Flash programming.

XTAL1 Input to the inverting oscillator amplifier and input to the internal clock operating circuit.

XTAL2 Output from the inverting oscillator amplifier





Special
FunctionA map of the on-chip memory area called the Special Function Register (SFR) space is shown
in Table 1.RegistersNote that not all of the addresses are occupied, and unoccupied addresses may not be imple-
mented on the chip. Read accesses to these addresses will in general return random data,
and write accesses will have an indeterminate effect.

B Image: Second s		A103031.0	n it inap and	Reset values			-
0000000 00000000 0	0F8H						0FFH
ACC 00000000 ACC 00000000 ACC 00000000 ACC 000 AUXR1 XXXXXXX AUXR1 XXXXXXXX AUXR1 VDTRST XXXXXXXX AUXR 0A AUXR 0	0F0H						0F7H
OEOH O000000 OE OE OE OE OBH PSW Image: Second S	0E8H						0EFH
DODH PSW 00000000 Image: Constraint of the symbol of the	0E0H						0E7H
ODH 00000000 Image: Constraint of the synthesis of the synthesyntex of the synthesyntex of the synthesynthesyntex of th	0D8H						0DFH
OCOH IP IC I	0D0H						0D7H
Image: Note of the synthesis of th	0C8H						0CFH
UBBH XX00000 Image: Constraint of the state of the s	0C0H						0C7H
UBOH 11111111 IE	0B8H						0BFH
OA8H OX000000 AUXR1 WDTRST OA OA0H P2 11111111 AUXR1 XXXXXXX0 Image: Constant of the state of the st	0B0H						0B7H
OAOH 1111111 XXXXXX0 XXXXXX OA 98H SCON 00000000 SBUF XXXXXXXX Image: Constraint of the second se	0A8H						0AFH
98H 00000000 XXXXXXX Image: Constraint of the second s	0A0H						0A7H
90H 11111111 Image: Constraint of the second secon	98H						9FH
88H 00000000 00000000 00000000 00000000 00000000 XXX00XX0 Arrowson 80H P0 SP DP0L DP0H DP1L DP1H PCON 871	90H						97H
	88H						8FH
	80H						87H

Table 1. AT89S51 SFR Map and Reset Values

AT89S51

User software should not write 1s to these unlisted locations, since they may be used in future products to invoke new features. In that case, the reset or inactive values of the new bits will always be 0.

Interrupt Registers: The individual interrupt enable bits are in the IE register. Two priorities can be set for each of the five interrupt sources in the IP register.

AUXR	A	Address = 8EH Reset Value = XXX00XX0B								
Not Bit Addressable	Э									
	-	Ι	_	WDIDLE	DISRTO	_	_	DISALE		
Bit	7	6	5	4	3	2	1	0		
– DISALE		Reserved for future expansion								
DIGALL	DISAL	Disable/Enable ALE DISALE Operating Mode								
	0	ALE	is emit	tted at a con	stant rate of	1/6 the o	scillator fr	equency		
	1	ALE	is activ	e only durin	g a MOVX o	r MOVC i	nstructior	ı		
DISRTO	Disab	le/Enab	le Rese	et out						
	DISR	ГО								
	0	Res	et pin is	s driven Higł	n after WDT	times out				
	1	Res	et pin is	s input only						
WDIDLE	Disab	le/Enab	le WDT	in IDLE mo	de					
WDIDLE										
0	WD	WDT continues to count in IDLE mode								
1	WD	Γ halts (counting	g in IDLE mo	ode					

Table 2. AUXR: Auxiliary Register

Dual Data Pointer Registers: To facilitate accessing both internal and external data memory, two banks of 16-bit Data Pointer Registers are provided: DP0 at SFR address locations 82H-83H and DP1 at 84H-85H. Bit DPS = 0 in SFR AUXR1 selects DP0 and DPS = 1 selects DP1. The user should always initialize the DPS bit to the appropriate value before accessing the respective Data Pointer Register.





Power Off Flag: The Power Off Flag (POF) is located at bit 4 (PCON.4) in the PCON SFR. POF is set to "1" during power up. It can be set and rest under software control and is not affected by reset.

Table 3. AUXR1: Auxiliary Register 1

	Table 5.		Ruxillary	Register	I					
	AUXR1									
	Addr	ess = A2H	1							
	Reset Value = XXXXXX0B						X0B			
	Not Bit Addressable									
		-	-	_	_	-	-	-	DPS	
	Bit	7	6	5	4	3	2	1	0	
	-	Reserv	ed for futu	ure expan	sion					
	DPS	Data Po	ointer Reg	ister Sele	ct					
		DPS								
		0	Sele	cts DPTR	Registers	DP0L, DF	POH			
		1	Sele	cts DPTR	Registers	DP1L, DF	P1H			
]
Memory Organization	MCS-51 o bytes eac			•		•	-		Memory. Up t	o 64K
Program Memory	If the \overline{EA}	oin is cor	nected to	o GND, a	all progra	m fetches	s are dired	cted to exte	rnal memory.	
0 ,									ses 0000H th	
		directed	l to interi	nal mem					through FFFF	
Data Memory	The AT89S51 implements 128 bytes of on-chip RAM. The 128 bytes are accessible via direct and indirect addressing modes. Stack operations are examples of indirect addressing, so the 128 bytes of data RAM are available as stack space.									
Watchdog Timer (One-time Enabled with Reset-out)	The WDT is intended as a recovery method in situations where the CPU may be subjected to software upsets. The WDT consists of a 14-bit counter and the Watchdog Timer Reset (WDTRST) SFR. The WDT is defaulted to disable from exiting reset. To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, it will increment every machine cycle while the oscillator is running. The WDT timeout period is dependent on the external clock frequency. There is no way to disable the WDT except through reset (either hardware reset or WDT overflow reset). When WDT overflows, it will drive an output RESET HIGH pulse at the RST pin.									
Using the WDT	To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, the user needs to service it by writing 01EH and 0E1H to WDTRST to avoid a WDT overflow. The 14-bit counter overflows when it reaches 16383 (3FFFH), and this will reset the device. When the WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must reset the WDT at least every 16383 machine cycles. To reset the WDT the user must write 01EH and 0E1H to WDTRST. WDTRST is a write-only register. The WDT counter cannot be read or written. When WDT overflows, it will generate an output RESET pulse at the RST pin. The RESET pulse duration is 98xTOSC, where TOSC=1/FOSC. To make the best use of the WDT, it									
- /										

	should be serviced in those sections of code that will periodically be executed within the time required to prevent a WDT reset.
WDT During Power-down and Idle	In Power-down mode the oscillator stops, which means the WDT also stops. While in Power- down mode, the user does not need to service the WDT. There are two methods of exiting Power-down mode: by a hardware reset or via a level-activated external interrupt, which is enabled prior to entering Power-down mode. When Power-down is exited with hardware reset, servicing the WDT should occur as it normally does whenever the AT89S51 is reset. Exiting Power-down with an interrupt is significantly different. The interrupt is held low long enough for the oscillator to stabilize. When the interrupt is brought high, the interrupt is serviced. To pre- vent the WDT from resetting the device while the interrupt pin is held low, the WDT is not started until the interrupt is pulled high. It is suggested that the WDT be reset during the inter- rupt service for the interrupt used to exit Power-down mode.
	To ensure that the WDT does not overflow within a few states of exiting Power-down, it is best to reset the WDT just before entering Power-down mode.
	Before going into the IDLE mode, the WDIDLE bit in SFR AUXR is used to determine whether the WDT continues to count if enabled. The WDT keeps counting during IDLE (WDIDLE bit = 0) as the default state. To prevent the WDT from resetting the AT89S51 while in IDLE mode, the user should always set up a timer that will periodically exit IDLE, service the WDT, and reenter IDLE mode.
	With WDIDLE bit enabled, the WDT will stop to count in IDLE mode and resumes the count upon exit from IDLE.
UART	The UART in the AT89S51 operates the same way as the UART in the AT89C51. For further information on the UART operation, refer to the ATMEL Web site (http://www.atmel.com). From the home page, select 'Products', then '8051-Architecture Flash Microcontroller', then 'Product Overview'.
Timer 0 and 1	Timer 0 and Timer 1 in the AT89S51 operate the same way as Timer 0 and Timer 1 in the AT89C51. For further information on the timers' operation, refer to the ATMEL Web site (http://www.atmel.com). From the home page, select 'Products', then '8051-Architecture Flash Microcontroller', then 'Product Overview'.
Interrupts	The AT89S51 has a total of five interrupt vectors: two external interrupts (INT0 and INT1), two timer interrupts (Timers 0 and 1), and the serial port interrupt. These interrupts are all shown in Figure 1.
	Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in Special Function Register IE. IE also contains a global disable bit, EA, which disables all interrupts at once.
	Note that Table 4 shows that bit position IE.6 is unimplemented. In the AT89S51, bit position IE.5 is also unimplemented. User software should not write 1s to these bit positions, since they may be used in future AT89 products.
	The Timer 0 and Timer 1 flags, TF0 and TF1, are set at S5P2 of the cycle in which the timers overflow. The values are then polled by the circuitry in the next cycle





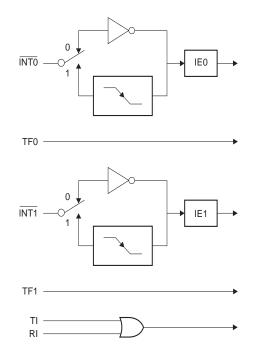
Table 4. Interrupt Enable (IE) Register

(N	ISB)	(LSB)							
	EA	_	_	ES	ET1	EX1	ET0	EX0	
E	Enable Bit = 1 enables the interrupt.								

Enable Bit = 0 disables the interrupt.

Symbol	Position	Function
EA	IE.7	Disables all interrupts. If $EA = 0$, no interrupt is acknowledged. If $EA = 1$, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.
_	IE.6	Reserved
_	IE.5	Reserved
ES	IE.4	Serial Port interrupt enable bit
ET1	IE.3	Timer 1 interrupt enable bit
EX1	IE.2	External interrupt 1 enable bit
ET0	IE.1	Timer 0 interrupt enable bit
EX0	IE.0	External interrupt 0 enable bit
User software should products.	I never write 1s to reser	ved bits, because they may be used in future AT89

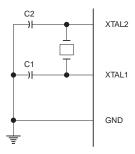
Figure 1. Interrupt Sources



Oscillator Characteristics

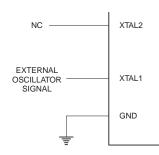
XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier that can be configured for use as an on-chip oscillator, as shown in Figure 2. Either a quartz crystal or ceramic resonator may be used. To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven, as shown in Figure 3. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum voltage high and low time specifications must be observed.

Figure 2. Oscillator Connections



Note: C1, C2 = 30 pF \pm 10 pF for Crystals = 40 pF \pm 10 pF for Ceramic Resonators

Figure 3. External Clock Drive Configuration



In idle mode, the CPU puts itself to sleep while all the on-chip peripherals remain active. The mode is invoked by software. The content of the on-chip RAM and all the special function registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

Note that when idle mode is terminated by a hardware reset, the device normally resumes program execution from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when idle mode is terminated by a reset, the instruction following the one that invokes idle mode should not write to a port pin or to external memory.

Power-down Mode In the Power-down mode, the oscillator is stopped, and the instruction that invokes Powerdown is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the Power-down mode is terminated. Exit from Power-down mode can be initiated either by a hardware reset or by activation of an enabled external interrupt into INT0 or INT1. Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before V_{CC} is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.





Mode	Program Memory	ALE	PSEN	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

Program Memory Lock Bits

The AT89S51 has three lock bits that can be left unprogrammed (U) or can be programmed (P) to obtain the additional features listed in the following table.

Table 6. Lock Bit Protection Modes

Program Lock Bits				
	LB1	LB2	LB3	Protection Type
1	U	U	U	No program lock features
2	Р	U	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, \overline{EA} is sampled and latched on reset, and further programming of the Flash memory is disabled
3	Р	Р	U	Same as mode 2, but verify is also disabled
4	Р	Р	Р	Same as mode 3, but external execution is also disabled

When lock bit 1 is programmed, the logic level at the \overline{EA} pin is sampled and latched during reset. If the device is powered up without a reset, the latch initializes to a random value and holds that value until reset is activated. The latched value of \overline{EA} must agree with the current logic level at that pin in order for the device to function properly.

Programming the Flash – Parallel Mode

The AT89S51 is shipped with the on-chip Flash memory array ready to be programmed. The programming interface needs a high-voltage (12-volt) program enable signal and is compatible with conventional third-party Flash or EPROM programmers.

The AT89S51 code memory array is programmed byte-by-byte.

Programming Algorithm: Before programming the AT89S51, the address, data, and control signals should be set up according to the Flash programming mode table and Figures 13 and 14. To program the AT89S51, take the following steps:

- 1. Input the desired memory location on the address lines.
- 2. Input the appropriate data byte on the data lines.
- 3. Activate the correct combination of control signals.
- 4. Raise \overline{EA}/V_{PP} to 12V.
- 5. Pulse ALE/PROG once to program a byte in the Flash array or the lock bits. The bytewrite cycle is self-timed and typically takes no more than 50 µs. Repeat steps 1 through 5, changing the address and data for the entire array or until the end of the object file is reached.

Data Polling: The AT89S51 features Data Polling to indicate the end of a byte write cycle. During a write cycle, an attempted read of the last byte written will result in the complement of the written data on P0.7. Once the write cycle has been completed, true data is valid on all outputs, and the next cycle may begin. Data Polling may begin any time after a write cycle has been initiated.

AT89S51

Ready/Busy: The progress of byte programming can also be monitored by the RDY/BSY output signal. P3.0 is pulled low after ALE goes high during programming to indicate BUSY. P3.0 is pulled high again when programming is done to indicate READY.

Program Verify: If lock bits LB1 and LB2 have not been programmed, the programmed code data can be read back via the address and data lines for verification. The status of the individual lock bits can be verified directly by reading them back.

Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 000H, 100H, and 200H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows.

(000H) = 1EH indicates manufactured by Atmel (100H) = 51H indicates 89S51 (200H) = 06H

Chip Erase: In the parallel programming mode, a chip erase operation is initiated by using the proper combination of control signals and by pulsing ALE/PROG low for a duration of 200 ns - 500 ns.

In the serial programming mode, a chip erase operation is initiated by issuing the Chip Erase instruction. In this mode, chip erase is self-timed and takes about 500 ms.

During chip erase, a serial read from any address location will return 00H at the data output.

Programming the Flash – **Serial Mode Serial Mode** The Code memory array can be programmed using the serial ISP interface while RST is pulled to V_{cc}. The serial interface consists of pins SCK, MOSI (input) and MISO (output). After RST is set high, the Programming Enable instruction needs to be executed first before other operations can be executed. Before a reprogramming sequence can occur, a Chip Erase operation is required.

The Chip Erase operation turns the content of every memory location in the Code array into FFH.

Either an external system clock can be supplied at pin XTAL1 or a crystal needs to be connected across pins XTAL1 and XTAL2. The maximum serial clock (SCK) frequency should be less than 1/16 of the crystal frequency. With a 33 MHz oscillator clock, the maximum SCK frequency is 2 MHz.

To program and verify the AT89S51 in the serial programming mode, the following sequence is recommended:

1. Power-up sequence:

Apply power between VCC and GND pins.

Set RST pin to "H".

If a crystal is not connected across pins XTAL1 and XTAL2, apply a 3 MHz to 33 MHz clock to XTAL1 pin and wait for at least 10 milliseconds.

- 2. Enable serial programming by sending the Programming Enable serial instruction to pin MOSI/P1.5. The frequency of the shift clock supplied at pin SCK/P1.7 needs to be less than the CPU clock at XTAL1 divided by 16.
- 3. The Code array is programmed one byte at a time in either the Byte or Page mode. The write cycle is self-timed and typically takes less than 0.5 ms at 5V.
- 4. Any memory location can be verified by using the Read instruction that returns the content at the selected address at serial output MISO/P1.6.
- 5. At the end of a programming session, RST can be set low to commence normal device operation.



Serial

Programming Algorithm

	Power-off sequence (if needed): Set XTAL1 to "L" (if a crystal is not used). Set RST to "L". Turn V _{cc} power off.
	Data Polling: The Data Polling feature is also available in the serial mode. In this mode, dur- ing a write cycle an attempted read of the last byte written will result in the complement of the MSB of the serial output byte on MISO.
Serial Programming Instruction Set	The Instruction Set for Serial Programming follows a 4-byte protocol and is shown in Table 8 on page 18.
Programming Interface – Parallel Mode	Every code byte in the Flash array can be programmed by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

All major programming vendors offer worldwide support for the Atmel microcontroller series. Please contact your local programming vendor for the appropriate software revision.

				ALE/	EA/						P0.7-0	P2.3-0	P1.7-0
Mode	v_{cc}	RST	PSEN	PROG	V _{PP}	P2.6	P2.7	P3.3	P3.6	P3.7	Data	Add	ress
Write Code Data	5V	н	L	(2)	12V	L	н	н	Н	н	D _{IN}	A11-8	A7-0
Read Code Data	5V	Н	L	н	Н	L	L	L	н	Н	D _{OUT}	A11-8	A7-0
Write Lock Bit 1	5V	н	L	(3)	12V	н	н	н	н	н	х	х	х
Write Lock Bit 2	5V	н	L	(3)	12V	н	н	н	L	L	х	х	х
Write Lock Bit 3	5V	н	L	(3)	12V	н	L	н	н	L	х	х	Х
Read Lock Bits 1, 2, 3	5V	н	L	н	Н	н	Н	L	н	L	P0.2, P0.3, P0.4	х	х
Chip Erase	5V	н	L	(1)	12V	н	L	н	L	L	х	х	Х
Read Atmel ID	5V	н	L	Н	Н	L	L	L	L	L	1EH	0000	00H
Read Device ID	5V	Н	L	н	н	L	L	L	L	L	51H	0001	00H
Read Device ID	5V	н	L	Н	Н	L	L	L	L	L	06H	0010	00H

 Table 7.
 Flash Programming Modes

Notes: 1. Each PROG pulse is 200 ns - 500 ns for Chip Erase.

2. Each PROG pulse is 200 ns - 500 ns for Write Code Data.

3. Each PROG pulse is 200 ns - 500 ns for Write Lock Bits.

4. RDY/BSY signal is output on P3.0 during programming.

5. X = don't care.

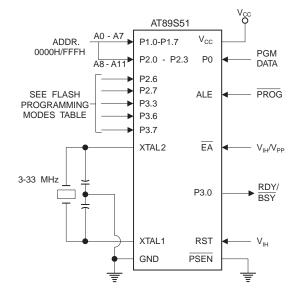
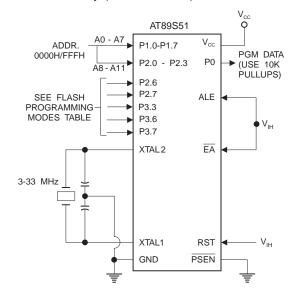


Figure 4. Programming the Flash Memory (Parallel Mode)

Figure 5. Verifying the Flash Memory (Parallel Mode)







Flash Programming and Verification Characteristics (Parallel Mode)

 $T_{\rm A}$ = 20°C to 30°C, $V_{\rm CC}$ = 4.5 to 5.5V

Symbol	Parameter	Min	Max	Units
V _{PP}	Programming Supply Voltage	11.5	12.5	V
I _{PP}	Programming Supply Current		10	mA
I _{CC}	V _{CC} Supply Current		30	mA
1/t _{CLCL}	Oscillator Frequency	3	33	MHz
t _{AVGL}	Address Setup to PROG Low	48t _{CLCL}		
t _{GHAX}	Address Hold After PROG	48t _{CLCL}		
t _{DVGL}	Data Setup to PROG Low	48t _{CLCL}		
t _{GHDX}	Data Hold After PROG	48t _{CLCL}		
t _{EHSH}	P2.7 (ENABLE) High to V _{PP}	48t _{CLCL}		
t _{SHGL}	V _{PP} Setup to PROG Low	10		μs
t _{GHSL}	V _{PP} Hold After PROG	10		μs
t _{GLGH}	PROG Width	0.2	1	μs
t _{AVQV}	Address to Data Valid		48t _{CLCL}	
t _{ELQV}	ENABLE Low to Data Valid		48t _{CLCL}	
t _{EHQZ}	Data Float After ENABLE	0	48t _{CLCL}	
t _{GHBL}	PROG High to BUSY Low		1.0	μs
t _{wc}	Byte Write Cycle Time		50	μs

Figure 6. Flash Programming and Verification Waveforms – Parallel Mode

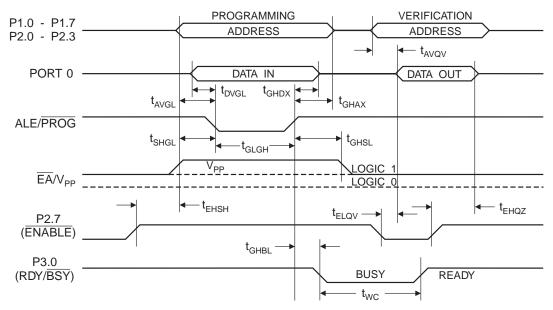
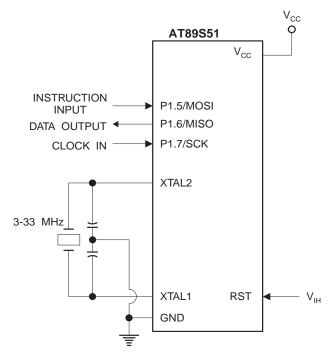


Figure 7. Flash Memory Serial Downloading



Flash Programming and Verification Waveforms – Serial Mode

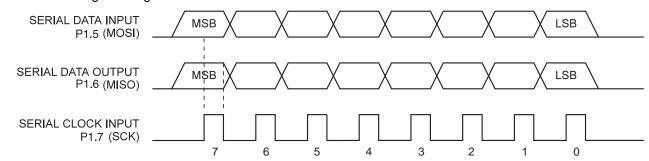


Figure 8. Serial Programming Waveforms





Table 8. Serial Programming Instruction Set

	Instruction Format				
Instruction	Byte 1	Byte 2	Byte 3	Byte 4	Operation
Programming Enable	1010 1100	0101 0011	XXXX XXXX	xxxx xxxx 0110 1001 (Output)	Enable Serial Programming while RST is high
Chip Erase	1010 1100	100x xxxx	XXXX XXXX	xxxx xxxx	Chip Erase Flash memory array
Read Program Memory (Byte Mode)	0010 0000	AA011 XXXX A0012 XXXX	AAAA 4567	0000 0000 0123 4500	Read data from Program memory in the byte mode
Write Program Memory (Byte Mode)	0100 0000	A4011 XXXX A9011 XXXX	AAAA AAAA 4567	7000 0000 7004 80700	Write data to Program memory in the byte mode
Write Lock Bits ⁽²⁾	1010 1100	1110 00 🚡 🔛	xxxx xxxx	xxxx xxxx	Write Lock bits. See Note (2).
Read Lock Bits	0010 0100	XXXX XXXX	XXXX XXXX	xx ^{EEE} ^{EE} xx	Read back current status of the lock bits (a programmed lock bit reads back as a "1")
Read Signature Bytes ⁽¹⁾	0010 1000	4234 5 XXX	[€] xxx xxxx	Signature Byte	Read Signature Byte
Read Program Memory (Page Mode)	0011 0000	A400 4001 8000 4000	Byte 0	Byte 1 Byte 255	Read data from Program memory in the Page Mode (256 bytes)
Write Program Memory (Page Mode)	0101 0000	A400 A50 800 10 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7	Byte 0	Byte 1 Byte 255	Write data to Program memory in the Page Mode (256 bytes)

Notes: 1. The signature bytes are not readable in Lock Bit Modes 3 and 4.

 B1 = 0, B2 = 0 → Mode 1, no lock protection B1 = 0, B2 = 1 → Mode 2, lock bit 1 activated B1 = 1, B2 = 0 → Mode 3, lock bit 2 activated B1 = 1, B1 = 1 → Mode 4, lock bit 3 activated

 \underline{Each} of the lock bits needs to be activated sequentially before Mode 4 can be executed.

After Reset signal is high, SCK should be low for at least 64 system clocks before it goes high to clock in the enable data bytes. No pulsing of Reset signal is necessary. SCK should be no faster than 1/16 of the system clock at XTAL1.

For Page Read/Write, the data always starts from byte 0 to 255. After the command byte and upper address byte are latched, each byte thereafter is treated as data until all 256 bytes are shifted in/out. Then the next instruction will be ready to be decoded.

Serial Programming Characteristics

Figure 9. Serial Programming Timing

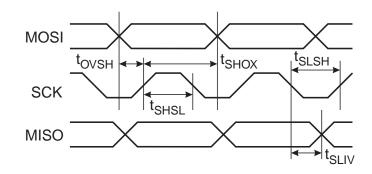


Table 9.	Serial Programming Characteristics	, Τ _Α	= -40° C to 85° C, V _{CC} = $4.0 - 5.5$ V (Unless Otherwise Noted)	
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Symbol	Parameter	Min	Тур	Max	Units
1/t _{CLCL}	Oscillator Frequency	0		33	MHz
t _{CLCL}	Oscillator Period	30			ns
t _{SHSL}	SCK Pulse Width High	8 t _{CLCL}			ns
t _{SLSH}	SCK Pulse Width Low	8 t _{CLCL}			ns
t _{OVSH}	MOSI Setup to SCK High	t _{CLCL}			ns
t _{SHOX}	MOSI Hold after SCK High	2 t _{CLCL}			ns
t _{SLIV}	SCK Low to MISO Valid	10	16	32	ns
t _{ERASE}	Chip Erase Instruction Cycle Time			500	ms
t _{SWC}	Serial Byte Write Cycle Time			64 t _{CLCL} + 400	μs





Absolute Maximum Ratings*

Operating Temperature55°C to +125°C
Storage Temperature65°C to +150°C
Voltage on Any Pin with Respect to Ground1.0V to +7.0V
Maximum Operating Voltage 6.6V
DC Output Current 15.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics

The values shown in this table are valid for $T_A = -40^{\circ}$ C to 85°C and $V_{CC} = 4.0$ V to 5.5V, unless otherwise noted.

Symbol	Parameter	Condition	Min	Max	Units
V _{IL}	Input Low Voltage	(Except EA)	-0.5	0.2 V _{CC} -0.1	V
V _{IL1}	Input Low Voltage (EA)		-0.5	0.2 V _{CC} -0.3	V
V _{IH}	Input High Voltage	(Except XTAL1, RST)	0.2 V _{CC} +0.9	V _{CC} +0.5	V
V _{IH1}	Input High Voltage	(XTAL1, RST)	0.7 V _{CC}	V _{CC} +0.5	V
V _{OL}	Output Low Voltage ⁽¹⁾ (Ports 1,2,3)	I _{OL} = 1.6 mA		0.45	V
V _{OL1}	Output Low Voltage ⁽¹⁾ (Port 0, ALE, PSEN)	I _{OL} = 3.2 mA		0.45	V
		$I_{OH} = -60 \ \mu A, \ V_{CC} = 5V \pm 10\%$	2.4		V
	Output High Voltage	I _{OH} = -25 μA	0.75 V _{CC}		V
V _{OH}	(Ports 1,2,3, ALE, PSEN)	I _{OH} = -10 μA	0.9 V _{CC}		V
		$I_{OH} = -800 \ \mu A, \ V_{CC} = 5V \pm 10\%$	2.4		V
	Output High Voltage	I _{OH} = -300 μA	0.75 V _{CC}		V
V _{OH1}	(Port 0 in External Bus Mode)	I _{OH} = -80 μA	0.9 V _{CC}		V
I _{IL}	Logical 0 Input Current (Ports 1,2,3)	V _{IN} = 0.45V		-50	μA
I _{TL}	Logical 1 to 0 Transition Current (Ports 1,2,3)	$V_{IN} = 2V, V_{CC} = 5V \pm 10\%$		-650	μA
I _{LI}	Input Leakage Current (Port 0, EA)	0.45 < V _{IN} < V _{CC}		±10	μA
RRST	Reset Pulldown Resistor		50	300	KΩ
C _{IO}	Pin Capacitance	Test Freq. = 1 MHz, T _A = 25°C		10	pF
		Active Mode, 12 MHz		25	mA
	Power Supply Current	Idle Mode, 12 MHz		6.5	mA
I _{CC}	Power-down Mode ⁽²⁾	V _{CC} = 5.5V		50	μA

Notes: 1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:

Maximum I_{OL} per port pin: 10 mA

Maximum I_{OL} per 8-bit port:

Port 0: 26 mA Ports 1, 2, 3: 15 mA

Maximum total I_{OL} for all output pins: 71 mA

If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

2. Minimum V_{CC} for Power-down is 2V.

AT89S51

AC Characteristics

Under operating conditions, load capacitance for Port 0, ALE/ \overline{PROG} , and $\overline{PSEN} = 100 \text{ pF}$; load capacitance for all other outputs = 80 pF.

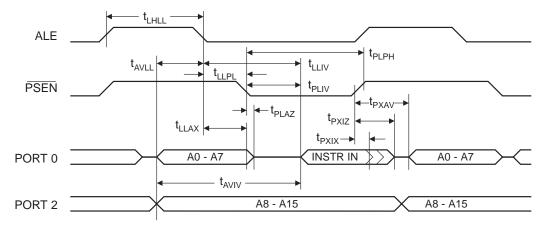
External Program and Data Memory Characteristics

		12 MHz (Oscillator	Variable			
Symbol	Parameter	Min	Мах	Min	Max	Units	
1/t _{CLCL}	Oscillator Frequency			0	33	MHz	
t _{LHLL}	ALE Pulse Width	127		2t _{CLCL} -40		ns	
t _{AVLL}	Address Valid to ALE Low	43		t _{CLCL} -25		ns	
t _{LLAX}	Address Hold After ALE Low	48		t _{CLCL} -25		ns	
t _{LLIV}	ALE Low to Valid Instruction In		233		4t _{CLCL} -65	ns	
t _{LLPL}	ALE Low to PSEN Low	43		t _{CLCL} -25		ns	
t _{PLPH}	PSEN Pulse Width	205		3t _{CLCL} -45		ns	
t _{PLIV}	PSEN Low to Valid Instruction In		145		3t _{CLCL} -60	ns	
t _{PXIX}	Input Instruction Hold After PSEN	0		0		ns	
t _{PXIZ}	Input Instruction Float After PSEN		59		t _{CLCL} -25	ns	
t _{PXAV}	PSEN to Address Valid	75		t _{CLCL} -8		ns	
t _{AVIV}	Address to Valid Instruction In		312		5t _{CLCL} -80	ns	
t _{PLAZ}	PSEN Low to Address Float		10		10	ns	
t _{RLRH}	RD Pulse Width	400		6t _{CLCL} -100		ns	
t _{wLWH}	WR Pulse Width	400		6t _{CLCL} -100		ns	
t _{RLDV}	RD Low to Valid Data In		252		5t _{CLCL} -90	ns	
t _{RHDX}	Data Hold After RD	0		0		ns	
t _{RHDZ}	Data Float After RD		97		2t _{CLCL} -28	ns	
t _{LLDV}	ALE Low to Valid Data In		517		8t _{CLCL} -150	ns	
t _{AVDV}	Address to Valid Data In		585		9t _{CLCL} -165	ns	
t _{LLWL}	ALE Low to RD or WR Low	200	300	3t _{CLCL} -50	3t _{CLCL} +50	ns	
t _{AVWL}	Address to RD or WR Low	203		4t _{CLCL} -75		ns	
t _{QVWX}	Data Valid to WR Transition	23		t _{CLCL} -30		ns	
t _{QVWH}	Data Valid to WR High	433		7t _{CLCL} -130		ns	
t _{WHQX}	Data Hold After WR	33		t _{CLCL} -25		ns	
t _{RLAZ}	RD Low to Address Float		0		0	ns	
t _{WHLH}	RD or WR High to ALE High	43	123	t _{CLCL} -25	t _{CLCL} +25	ns	

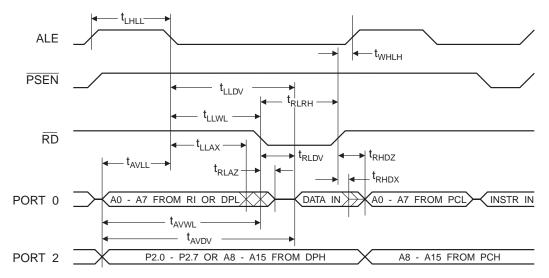




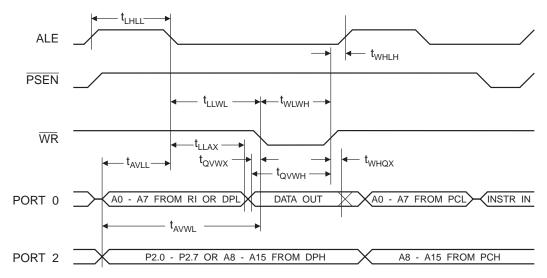
External Program Memory Read Cycle



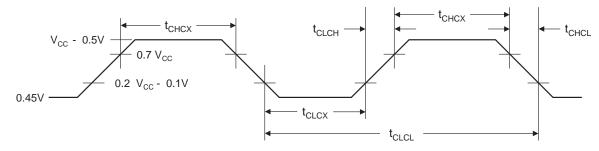
External Data Memory Read Cycle



External Data Memory Write Cycle



External Clock Drive Waveforms



External Clock Drive

Symbol	Parameter	Min	Max	Units
1/t _{CLCL}	Oscillator Frequency	0	33	MHz
t _{CLCL}	Clock Period	30		ns
t _{CHCX}	High Time	12		ns
t _{CLCX}	Low Time	12		ns
t _{CLCH}	Rise Time		5	ns
t _{CHCL}	Fall Time		5	ns



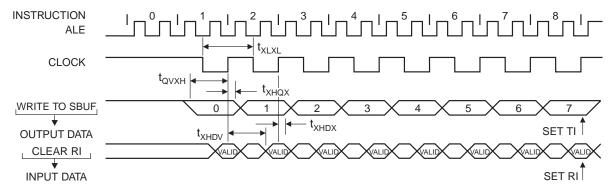


Serial Port Timing: Shift Register Mode Test Conditions

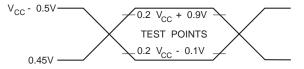
The values in this table are valid for V_{CC} = 4.0V to 5.5V and Load Capacitance = 80 pF.

		12 MI	Hz Osc	Variable (
Symbol	Parameter	Min	Max	Min	Max	Units
t _{XLXL}	Serial Port Clock Cycle Time	1.0		12t _{CLCL}		μs
t _{QVXH}	Output Data Setup to Clock Rising Edge	700		10t _{CLCL} -133		ns
t _{XHQX}	Output Data Hold After Clock Rising Edge	50		2t _{CLCL} -80		ns
t _{XHDX}	Input Data Hold After Clock Rising Edge	0		0		ns
t _{XHDV}	Clock Rising Edge to Input Data Valid		700		10t _{CLCL} -133	ns

Shift Register Mode Timing Waveforms

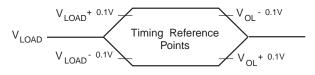


AC Testing Input/Output Waveforms⁽¹⁾



Note: 1. AC Inputs during testing are driven at V_{CC} - 0.5V for a logic 1 and 0.45V for a logic 0. Timing measurements are made at V_{IH} min. for a logic 1 and V_{IL} max. for a logic 0.

Float Waveforms⁽¹⁾



Note: 1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs.

Speed (MHz)	Power Supply	Ordering Code	Package	Operation Range
24	4.0V to 5.5V	AT89S51-24AC	44A	Commercial
		AT89S51-24JC	44J	(0° C to 70° C)
		AT89S51-24PC	40P6	
		AT89S51-24AI	44A	Industrial
		AT89S51-24JI	44J	(-40° C to 85° C)
		AT89S51-24PI	40P6	
33	4.5V to 5.5V	AT89S51-33AC	44A	Commercial
		AT89S51-33JC	44J	(0° C to 70° C)
		AT89S51-33PC	40P6	

Ordering Information

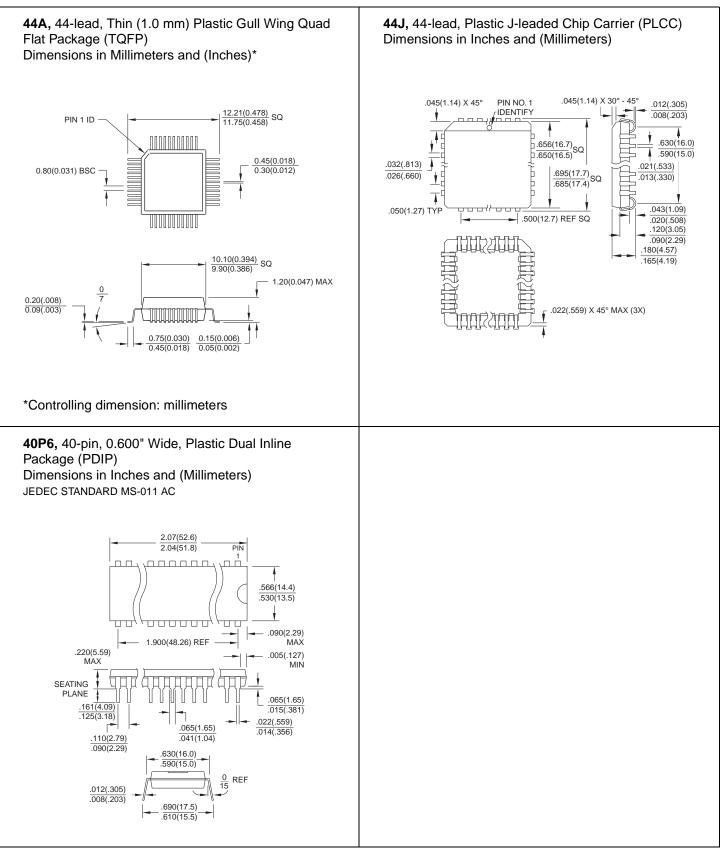
= Preliminary Availability

Package Type	
44A	44-lead, Thin Plastic Gull Wing Quad Flatpack (TQFP)
44J	44-lead, Plastic J-leaded Chip Carrier (PLCC)
40P6	40-pin, 0.600" Wide, Plastic Dual Inline Package (PDIP)





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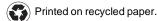
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